



EXPRESS MAIL NO. EV207744057US

PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Giovanni Frezza  
Application No. : 09/997,995  
Filed : November 30, 2001  
For : METHOD FOR FORMING A PROTECTIVE  
PACKAGE FOR ELECTRONIC CIRCUITS

Examiner : Quang D. Vu  
Art Unit : 2811  
Docket No. : 856063.722  
Date : December 3, 2002

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TECHNOLOGY CENTER 2800

Commissioner for Patents  
Washington, DC 20231

AMENDMENT

Commissioner for Patents:

In response to the Office Action dated July 3, 2002, please extend the period of time for response two months, to expire on December 3, 2002. Enclosed are a Petition for an Extension of Time and the requisite fee. Please amend the application as follows:

In the Specification:

Please replace the paragraph beginning at page 4, line 14, with the following rewritten paragraph:

a1  
Advantageously, a ring 52 is provided on the cap of the sensor 30, which is formed out of semiconductor material, for example. This ring 52 is filled with the covering layer 50 material. Thus, the ring 52 will form a barrier or containing dyke for the covering layer 50.

Please replace the paragraph beginning at page 6, line 3, with the following rewritten paragraph:

a2  
In this embodiment it is only necessary that the projecting portion 51 abuts against the lug 13, so that the formation of the projecting portion 51 is less critical.